

Abstract

A semiconductor-chip mounting substrate with a high degree of reliability of an electrical connection between a substrate and a semiconductor chip such as IC chips is provided. The substrate has at least one projection thereon, which is integrally molded with the substrate. A conductive layer is formed on the projection to obtain a first bump. The semiconductor chip has a terminal projecting as a second bump on its surface. The semiconductor chip is mounted on the substrate such that the first bump contacts the second bump. A required contact pressure between the first bump and the second bump is held by use of a pressure holding means.

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